TENTATIVE SCHEDULE: INTERNATIONAL SOURCING PROGRAME (INSP) ON ELECTRICAL & ELECTRONICS PRODUCT KUALA LUMPUR, MALAYSIA

10-12 AUGUST 2016

10 AUGUST 2016 (WEDNESDAY)

: All day Buyers Arrival

: Buyers Check-in at Hotel (TBA)

11 AUGUST 2016 (THURSDAY)

8.30 AM : Buyers depart from Hotel to Menara MATRADE

9.30 AM : Welcoming Remarks

9.40 AM : Introduction of Buyers

10.00 AM : One-on-One Business Meetings

1.00 PM : Lunch

2.00 PM : Continuation of One-on-One Business Meetings

5.00 PM : End of One-on-One Business Meetings

5.30 PM : Buyers depart for Hotel

12 AUGUST 2016 (FRIDAY)

8.30 AM : Buyers depart from hotel for **Group Programme**

9.30 AM : Group Programme

12.00 NOON : End of Group Programme

: Buyers depart for hotel

13 AUGUST 2016 (SATURDAY)

: Buyers check-out from Hotel

: Buyers departure to KLIA (On individual Basis/By Request)

END OF PROGRAMME

LETTER OF UNDERTAKING

INTERNATIONAL SOURCING PROGRAMME (INSP) ON ELECTRICAL & ELECTRONIC PRODUCTS & SERVICES, KUALA LUMPUR, MALAYSIA, 10 – 12 AUGUST 2016

I,(Passport No.:)
hereby acknowledge that:
Upon being selected by MATRADE to participate in this programme :
 I will attend the arranged meeting sessions and if I fail to do so, I will bear the total cost of the accommodation; and
 If I cancel my participation <u>after 18th July 2016</u>, I will be charged with any penalty imposed by the hotel.
I have read the above statements and agree to abide by the terms.
Yours sincerely,
Name :
Date :
Company stamp :





INTERNATIONAL SOURCING PROGRAMME (INSP) ON ELECTRICAL & ELECTRONIC PRODUCTS & SERVICES, KUALA LUMPUR, MALAYSIA 10-12 AUGUST 2016

TO **MATRADE**

DATELINE: 31 MAY 2016 REPLY FAX

ATTENTION

My company is interested to participate in this programme:

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Category of Business End User									Priv	/ate	Sec	tor			Pul	blic/	Gov	erni	nen	t												
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- Important Notes:

 1) Complimentary hotel accommodation of one room (single or double) is provided for each company for 4 days & 3 nights stay [check in 10 August 2016 & check out 13 August 2016].
- 2) Participants will pay on their own for extra room and all other incidental charges i.e. local & long distance call, room service, mini bar, laundry and other related hotel services used.
- 3) Although MATRADE is paying for the hotel room, you will be required to provide a credit card information. Please note that the credit card details will be deemed as strictly **confidential** and its purpose is to guarantee for no show up from buyers (please refer Buyers Letter Of Undertaking).
- 4) Participants are required to provide the flight details for arrival and departure to / from KLIA in order for MATRADE to arrange airport and hotel transfers.
- 5) Application to participate in this programme is subject to approval by MATRADE and successful companies will be notified officially.

Main Category	Product / Services Description
100 Device Manufacturers	Foundry Contract Manufacturing Services - Wafer Processing or MEMS
100 Device Manaractarers	Micro Electro Mechanical Systems (MEMS); Micro Machines
101 Photovoltaic Device	PV: Cells
	PV: Modules PV: Stand-Alone Systems
Manufacturing	PV-Building-Integrated Solutions
	Solar Thermal
	Backgrind; Slicing; Lapping; Polishing Equipment
	Ball Placement; Attach Systems Base Loader Systems
	Cleaning; Washing Equipment for Assembly & Packaging
	Cut & Down Set; Trim; Form Equipment Deflashing; Degating Tools
	Device Handling; Feeding Systems
	Dicing; Sawing; Scribing; Separation Equipment Die Bonding; Attach Equipment
	Die Removal Equipment
	Die Sorter; Pick & Place; Flip Chip Placement Systems Dispensing Systems
	Hot Embossing System
200 Equipment, Assembly	Lead Finishing; Straightening Equipment Lead frame Taping Systems
	Lithography Systems for Wafer Level Packaging; Bumping; 3D Interconnect Aligners
	Marking; Imprinting; Labeling Equipment Molding; Encapsulation; Decapsulation Equipment
	Package Handling; Conveying Equipment
	Package Simulation; Characterization Equipment Plating; Electro Chemical Plating for Device assembly
	Printing Equipment; Screen-printing; Alignment; Film Printing
	PROM; Memory Programmer Equipment Solder Reflow; Soldering & Brazing Equipment
	T
	Tape Automated Bonding (TAB); Bumped Tape Automated Bonding (BTAB) Equipment Wafer Level Bonders
	Wafer Mount; Taping Equipment Wire Bonding Equipment
	Wite bonding equipment
	Cutting; Drilling; Laser ablation; Beveling Equipment Heating; Annealing; Curing Equipment - Furnaces; Conveyors; Ovens; Test Chambers; Heat
	Treating
202 Farriage ant Compared Han	Lamination; Sheet Laminating Equipment Repair; Rework Equipment
202 Equipment, General Use	Sealing; Bagging; Packing Equipment
	Space simulation; Vacuum chambers Vacuum drying & out gassing Systems
	Vibration Isolation Systems
	Vision; ID; Bar Code Systems Welding Equipment
	Acoustic Spectroscopy; Electron Spectroscopy for Chemical Analysis (ESCA); Ultrasonic;
	Acoustical Microscopes
	Air Velocity (VA); Humidity and Moisture Sensing Centrifuges
	Chromatograph
	CV (capacitance-to-voltage) Probe Systems Defect; Particle; Bump; Contamination Detection, Review or Inspection
	Die Inspection; Die Shear
	Fiber Optic Inspection Instruments Film Thickness; Thickness; Uniformity Measurement; Ellipsometer
	Flat; Notch Finding System
	Instruments; Bench Top Test Leak Detection Systems - Vacuum or Gas
	Line Width; Critical Dimension (CD) Measurement
203 Equipment, Inspection &	Microscopes: Atomic Force Microscopes (AFM) Microscopes: Confocal Scanning Microscope; 3-D Video Microscopes
Measurement	Microscopes: Optical Microscopes
Wicasarcinent	Microscopes: Scanning Electron Microscope (SEM); Focused Ion Beam (FIB), Transmission Electron Microscope (TEM)
	Overlay Measurement
	Package Inspection; Lead Scanners Particle Monitors; Analyzers - Airborne or Liquid
	Plate Inspection Equipment

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	Resistivity Measurement; 4 point probe; Sheet resistance						
	Spectrometers; Fourier Transform Infrared (FTIR); Attenuated Total Reflectance FTIR (ATR-FTIR);						
	Auger Electron (AES); SIMS Stress; Refractive Index; Reflectivity & Conductivity Measurement						
	Thermal Sensing; Measurement; Analysis Wafer; Substrate Metrology; Topology; Nanotopography; Flatness Measurement; Crystalline						
	Orientation						
	Weight Measurement; Precision Scales						
	Wire Bonding Inspection; Test						
	X-ray; XRF; 3-D X-Ray; Lexes Systems						
	A-lay, All , 3-0 A-lay, Lexes systems						
	Deep RIE etching; Dry etching						
204 Equipment, MEMS	Double sided mask aligner						
	Wafer Level Bonders						
205 5							
205 Equipment,							
Nanotechnology	Equipment Nanotechnology						
Nanotechnology	Equipment, Nanotechnology						
	Cells						
	Inspection and Metrology						
200 51/ 5	Integration and Automation						
206 PV Equipment	Modules						
	Other						
	Thin Film						
	Wafers						
	Bumping Systems						
	- F 0-7/						
	Chemical Mechanical Polishing (CMP); Electro Polishing; Mechanical Polishing Equipment						
	Cleaning; Washing; Drying Equipment for Substrate; Fab Processing						
	Coat; Develop; Resist Processing; Track Equipment						
	Crystal Growing & Machining Equipment						
	Deposition; Chemical Vapor (CVD); MOCVD; PECVD; ALD/REALD; LPCVD; MVD						
	Deposition; Physical Vapor (PVD); Sputtering; Evaporation Equipment						
	Environmental Enclosures; Minienvironments						
207 Equipment, Process	Epitaxy Equipment; Epi Reactors; Molecular Beam Epitaxy (MBE); Atomic Layer Epitaxy (ALE)						
' ' '	Etching; Stripping; Ashing - Dry and Wet Equipment						
	Ion Implantation Equipment						
	lon; E Beam Milling Etching Equipment						
	Lithography; Exposure - Aligners; Direct Write Systems; Steppers; Scanners; Nanoimprint						
	Plating; Electro Chemical Plating; Deposition Systems						
	SOI Bonders; Temporary Bonders; De-Bonders						
	Spin on Glass (SOG); on Dielectric (SOD) Track systems						
	Thermal Processing - Diffusion; Oxidation; Annealing; RTA; RTP Equipment						
	Transfer Systems for Wafer; Reticles or FPD's						
	Transfer Systems for Wafer; Reticles or FPD's Wafer Identification; Marking Equipment						
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	Marking ink
	Molding; Encapsulation; Potting; Resin Materials
	Package Substrates; Laminate; Film based
	Packages; Ceramic and Other High Temp compounds
300 Materials, Assembly	Packages; Plastic
300 1114131141317133311317	Preforms; Lids
	Printed Circuit Boards (PCB); Printed Wire Boards (PWB)
	Printing Masks; Screens Scribe Tools; Saw or Dicing Blades and Accessories
	Solder; Solder Balls and other Soldering Materials
	Tape & Reel Materials
	Tape Automated Bonding (TAB) Accessories
	Thermal Interface Materials; Heat Sinks
	Thick Film Pastes; Materials
	Thin Film; Dielectric Film Materials
	,
	Acids; Etchants
	Buffers; Alkalis; Bases
	Cleaning Chemicals; Solvents; Strippers
201 Materials Chamicals 9	DI; UP Water
301 Materials, Chemicals &	Dopants; liquid or solid
Solids	Other Specialty Chemicals
Julius	Photo Resist; Developers & Ancillaries (incl. Adhesion promoter (HMDS); Primer; Anti-Reflective
	Coating (ARC); BARC; TARC
	Solids
	Spin on glass material
	Surface protection material; coatings
202 14	
303 Materials, Gases	Comp Materials
	Gases Materials
304 Materials, Mask Making	
	Mask Making Materials
20E Materials	
305 Materials,	
Nanotechnology	
Nanotechnology	Materials, Nanotechnology
	Cell Materials Gases and Liquid Chemicals
306 PV Materials	Consumables
	Ingots, Wafers Other
	Solar Glass, encapsulation
	Solal Glass, encapsulation
	CMP; Grind; Lap; Polish; Abrasive materials
207.4.	Deposition Supplies
307 Materials, Process	Plating Materials
,	Truting Muterius
	Quartz ware (Silicon Carbide, Fused Quartz Glass, Sapphire), Ceramic & Oxide Ceramic Fixtures
200 Mail a dalla Collegia	
308 Materials, Substrate	Substrate Materials
	Burn-In Boards; Performance Boards (incl. Low; High Temp and Ceramic)
200 Matariala Tast	Probe Cards; DUT boards and other probing accessories (incl Ceramic and Special Purpose Probe
309 Materials, Test	Cards)
	Structural Circuits; Test; Thermal Fixturing
	Test Sockets; Contactors and Contact accessories
	Bearings; Shaft Collars
	Chucks for Wafer and other Substrates
	Computer Accessories; Peripherals; Upgrades; Service
	Connectors; Plugs; Interconnects; Cable; Wire
	Electronic Hardware; Fixtures and Supplies
	Enclosures; Cabinets
	Fasteners; General Hardware
	Filters for Liquid; Oil
	Filters, Getters, Purifiers, Catalysts for Gases
	Flow Control Components - Valves; Meters; Gauges; Regulators; MFC's
	Gaskets; Seals; O rings; Elastomers; Resins
400 Components, Parts &	
100 components, raits &	Heating Elements; coils; insulation; Temp Controls; vestibule blocks and other Furnace
Accessories	Indicator Status Lights
7.0000001100	Lamps (non Lithography), all type UV; LED and other
	Lamps for Lithography
	Magnetic Components; Heads
	Motors; Fans; Electric Rotary Spindles
I	Piezo Electronic Components

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	Pipe; Tubing; Hose; Flanges; Connectors; Couplings; Plumbing Fittings Raw Material & Custom Components; Metal							
	Raw Material & Custom Components; Metal Raw Material & Custom Components; Plastic							
	Sealants; Adhesives; Finishes							
	Sensors							
	Vacuum Systems Components & Accessories (optical monitors; Sputtering target fixtures;							
	lubricants; pump oils; etc.)							
	Windows							
	Braking Systems							
	Cameras - Still; CCD; Video & Monitors							
	Computer; Control; Communication; Data Acquisition Systems							
	Exposure; Illumination Sources - Laser; Lamp; X-ray & other							
	Gas; Liquid delivery panels as subsystems							
	Gear Reducers; Gearheads; Geardrives							
	Handling; Transfer; Loading Systems; Lifting Devices Hydraulic Systems							
401 Sub-systems	Motion control systems; Servo control systems & Components							
TOT SUB SYSTEMS	Optics; Lens Products; Auto-Focus Systems							
	Plasma Sources; Controls; Monitoring; Diagnosis							
	Pneumatic Systems; Pneumatic rotary spindles							
	Power Supplies; RF Generators; Converters; Electrical Conditioning							
	Process Monitoring Systems Pumps, for Fluids							
	Pumps, Vacuum							
	Temperature Control; Recirculators; Chillers; Heat Exchangers							
	Ultrasonic Generators; Transducer and Monitoring Systems							
402 51/6	Chargers, Batteries							
402 PV Systems	Inverters Table 1							
	Measurement and Control Technology							
	Stand-Alone Systems							
403 PV Components, Tracking								
and Mounting Systems								
and Mounting Systems	Cables, Connectors, Junction Boxes							
	Chemical; Pure Water; Fluid Handling; Storage; Control; Supply Systems							
	Chemical; Pure Water; Fluid Monitoring & Control Systems Data Collection; Building control systems							
	Electrical; Power Distribution							
	Emergency (fire) & Security Control Systems							
500 Factory Monitoring &	Environmental; Utility Systems & Monitoring							
,	Equipment Interface; Communication Protocols							
Control Systems (FMCS)	Gas and Other Generation Systems							
	Gas Handling - Cabinets; Control; Supply Systems							
	Gas Monitoring Equipment; RGA's; TGO compliance							
	Logistics; Floor Control Systems Process Controls							
	Waste Control; Effluent Management Systems (Fluid & Gas; Exhaust Conditioning; Scrubbers)							
501 HVAC, Temperature,	Clean Rooms							
•	Contamination Control; HEPA Filtering Systems							
Humidity, Contamination Control	HVAC: Tomporature: Humidity Systems and Control							
	HVAC; Temperature; Humidity Systems and Control							
502 Material Handling	Conveying; Material Handling Systems							
	Robotics; Transfer Systems							
Systems	Static; ESD Control							
•	Stockers; Storage, AMHS							
600 Communication Software								
	Equipment Interface; Communication Protocols							
504 5 1 6 5								
601 Design Software	CAD - Computer Automated Design							
-	EDA - Electronic Design Automation; Circuit Design							
	CAM or CIM - Computer Aided Maguifacturing: Computer Integrated Manufacturing							
	CAM or CIM - Computer Aided Manufacturing; Computer Integrated Manufacturing Factory Automation; Cell Controller Software							
602 Manufacturing Software	Manufacturing Execution Software (MES)							
Joz Manaractaring Johtware	Production Control software							
	Test Programs							
	Yield Management; Process Control Software							
603 Simulation, Analysis;	Mask Making software & simulation							

Modeling Software	Package Simulation; Characterization Software						
Wodeling Software	Statistical Analysis; Modeling; Cost of Ownership (CoO) Software						
	Burn-In Service						
	Calibration & Reference Standards						
	Certification; Compliance; Independent Laboratories						
	Deposition Service						
	Etch; Strip; Cleaning Service						
	Failure Analysis and other Analytical Services						
	lon Implant Service Machine Shop; Fabrication Service						
	Mask Making Fabrication and Repair						
700 Manufacturing Services	Measurement; Inspection						
_	Micro Machining (small hole drilling and milling) services						
	Parts Cleaning; Micro Contamination						
	Plating; Electro Polishing; Coating; Surface Treatment						
	Reclaim Services (Evaporation; sputtering source material; Precious metal reclaim; Scrap;						
	Vacuum pump oil; Wafer reclaim)						
	Repair; Rebuild; Install Equipment; Maintenance Services; Spare Parts						
	Sawing; Lapping; Grinding; Polishing						
	Used; Rental Equipment; Inventory Reduction, Appraisal - Brokers; Resellers						
	Wafer Bumping Service						
	Assembly						
	Automation & Robotics						
	CAD; CAM; CIM						
	Circuit Design; Electronic Design Services (EDS); System Level Design (SLD)						
	Clean Room; Contamination Control						
	Environmental; Health & Safety and Hazardous Material (HazMat)						
	Equipment; Hardware; Product Design; Integration and Manufacturing						
701 Manufacturing Services or	Facilities; Building Environmental Systems Design & Monitoring; Alternative Energy Solutions						
Consulting	Facility Design; Construction; Architectural						
Consulting	Factory; Industrial Control; Utilization & Automation						
	Flat Panel Display (FPD) Design & Manufacturing Manufacturing Process Support and Development						
	Package Materials; Interconnect; SubComponent; SubAssembly Design Services						
	Product Development; Software Design; Product Lifecycle Management						
	Software Programming; Software Development						
	Static; ESD Testing & Control Services						
	Technical Intelligence; Reverse Engineering						
	Test						
	Wafer Handling						
800 Associations	Associations; Trade or Industrial						
OUU ASSUCIATIONS	Professional Societies						
901 Distribution and Logistics							
801 Distribution and Logistics							
	Distribution and Logistics						
802 Educational; Research							
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Institutions	Educational and Research Institutions						
	Market Studies; Market Research Organizations						
004.5 5 1.5 1	Marketing or Sales Consultants						
804 Professional Services	Operations; Management Consulting						
	Publications or Magazines; Printing						
	Purchasing; Procurement; Materials; Supply Chain Management Services						
	Sales; Manufacturers Representation or Distributors						
005 01/2	Education, Training						
805 PV Services	Organization, Association						
	Research and Development						
	·						
	Analytical Standards; Calibrators						
	Clean Room Supplies; Cleaning Supplies						
000 5	Device; Wafer; Display Panel Handling						
900 Support Products	Furniture; Storage; Cabinets						
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	Garments; Apparel						
	Laboratory Apparatus and Supplies						